

EDERC2014

Embedded Design in Education & Research Conference

11-12 September, 2014 • Milano - Italy



CALL FOR PAPERS DEADLINE HAS BEEN EXTENDED TO 16TH JUNE



Organising Committee:

GENERAL CHAIRS

John Soraghan
University of Strathclyde, UK
Djordje Marinkovic
Texas Instruments, Europe

TECHNICAL CHAIRS

Gaetano Di Caterina
University of Strathclyde, UK

WORKSHOPS and SHOW&TELL DEMOS

Nuria Llin
Texas Instruments, Europe
Keith Thompson
University of Strathclyde UK

PUBLICITY

Nuria Llin
Texas Instruments, Europe
Carmine Clemente
University of Strathclyde, UK

For more information, please contact:

EDERC2014 SECRETARIAT

Katja Palsson
Texas Instruments
Deutschland GmbH
Haggertystr. 1
85356- Freising – Germany

k-palsson@ti.com

Tel: +49-(0) 8161804979

Important Dates:

March 24th:

Proposals for special sessions

May 12th:

Proposals for tutorials/hands-on

May 26th - June 16th:

Electronic submission of papers

July 14th:

Notification of acceptance

August 4th:

Submission of camera ready paper

August 11th:

Early /Author Registration deadline

September 11th - 12th:

EDERC2014 Milan

We are delighted to announce a **Call for Papers** for the 6th **EDERC Conference** (European Embedded Design in Education and Research), to be held at the **Cosmo Hotel Palace, Milan, Italy**, September 11th and 12th 2014. EDERC2014 receives technical co-sponsorship from IEEE Region 8, IEEE Italian Signal Processing Chapter, and the IEEE IAS-PELS-IES North Italy Joint Chapter and the European Association of Signal Processing (EURASIP), in cooperation with Texas Instruments. The event aims to gather **educators and researchers** from around the world to share their experiences in the use of **DSP, microcontrollers** and **analog** technologies for **embedded systems**.

For the first time, **EDERC2014** will include an **analog signal processing systems track** that will incorporate smart sensing solutions including ultra-low power front end signal processing to detect “events” from vibrational, acoustic, magnetic, current, image or other analog sensors. Combining analog pre-processing with digital signal processing for optimum solutions is of particular interest.

Accepted papers will describe critical implementation issues and the latest applications of Texas Instruments embedded processors for a wide range of exciting applications. All papers will be indexed in **IEEE Xplore**. The conference will comprise **key note** addresses from industrial and academic experts, **oral, poster, show & tell demo sessions, and free workshops** (limited spaces) with tools.

Areas of Interest:

Submissions are invited in, *but not limited to*, the following areas:

DSP/microcontrollers/analog signal processing, smart sensor solutions, embedded processing technology in education and research using any of TI's multicore/DSP embedded processors and TI's analog technologies for:

- Power electronics, power management, digital power and control, motor drives
- Multimedia, 3D-imaging, compressed sensing, security and surveillance systems, smart cameras
- Communications: wired/wireless, SDR, broadband/UWB, internet, VOIP, optical
- Applications including: renewables, smart grid, biomedical, defence, radar and sonar, acoustics, aeronautics, automotive, transport, remote sensing, sensor networks, robotics, distributed collaborative systems, signal estimation and detection

Submission:

Procedures to submit a paper or proposal for special sessions using EDAS can be found at www.ti.com/ederc2014. Submitted papers must be camera-ready, no more than five pages long, and conform to the format specified on www.ti.com/ederc2014.

The early bird registration **cost of 199 Euro** will cover the registration fee, lunches, and refreshments for the two days, the EDERC2014 gala dinner and access to up to two hands-on workshops with tools. Furthermore, **a second person** from the same institution **may register for 50%** of the registration fee up to 11th August 2014. After 11th August 2014, the registration cost will be 249 Euro.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com